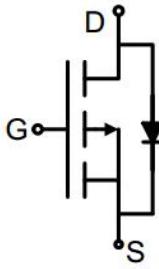
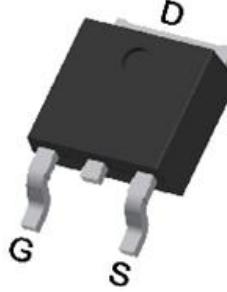


## P-Channel Enhancement Mode Power MOSFET

<p><b>Description</b></p> <p>The GT2K6P15K uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge. It can be used in a wide variety of applications.</p> <p><b>General Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS}</math> -150V</li> <li>● <math>I_D</math> (at <math>V_{GS} = -10V</math>) -11A</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = -10V</math>) &lt; 260mΩ</li> <li>● 100% Avalanche Tested</li> <li>● RoHS Compliant</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Power switch</li> <li>● DC/DC converters</li> </ul>	 <p>Schematic diagram</p>  <p>TO-252</p>
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<b>Ordering Information</b>			
<b>Device</b>	<b>Package</b>	<b>Marking</b>	<b>Packaging</b>
GT2K6P15K	TO-252	GT2K6P15	2500pcs/Reel

<b>Absolute Maximum Ratings</b> $T_C = 25^\circ\text{C}$ , unless otherwise noted				
<b>Parameter</b>		<b>Symbol</b>	<b>Value</b>	<b>Unit</b>
Drain-Source Voltage		$V_{DS}$	-150	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	$I_D$	-11	A
	$T_C = 100^\circ\text{C}$		-7	
Pulsed Drain Current	(note1)	$I_{DM}$	-44	A
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Power Dissipation		$P_D$	58	W
Single pulse avalanche energy	(note2)	$E_{AS}$	56	mJ
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55 To 150	°C

<b>Thermal Resistance</b>				
<b>Parameter</b>		<b>Symbol</b>	<b>Value</b>	<b>Unit</b>
Thermal Resistance, Junction-to-Ambient		$R_{thJA}$	50	°C/W
Thermal Resistance, Junction-to-Case		$R_{thJC}$	2.2	°C/W

**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-150	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = -150\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	-1	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-2.6	-3.0	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -5\text{A}$	--	205	260	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = -5\text{V}, I_D = -5\text{A}$	--	14	--	S
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -75\text{V}, f = 1.0\text{MHz}$	--	1400	--	pF
Output Capacitance	$C_{\text{oss}}$		--	60	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	1	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = -75\text{V}, I_D = -5\text{A}, V_{\text{GS}} = -10\text{V}$	--	36	--	nC
Gate-Source Charge	$Q_{\text{gs}}$		--	4	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	8	--	
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{\text{DD}} = -75\text{V}, I_D = -5\text{A}, R_G = 1.6\Omega$	--	26	--	ns
Turn-on Rise Time	$t_r$		--	7	--	
Turn-off Delay Time	$t_{d(\text{off})}$		--	28	--	
Turn-off Fall Time	$t_f$		--	12	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_s$	$T_C = 25^\circ\text{C}$	--	--	-11	A
Body Diode Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}, I_{SD} = -5\text{A}, V_{GS} = 0\text{V}$	--	--	-1.2	V
Reverse Recovery Charge	$Q_{rr}$	$I_F = -5\text{A}, V_{GS} = 0\text{V}$ $dI/dt = -100\text{A/us}$	--	150	--	nC
Reverse Recovery Time	$T_{rr}$		--	37	--	ns

**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=-50\text{V}$ ,  $V_{GS}=-10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$

The table shows the minimum avalanche energy, which is 156mJ when the device is tested until failure

3. Identical low side and high side switch with identical  $R_G$

Gate Charge Test Circuit



Switch Time Test Circuit

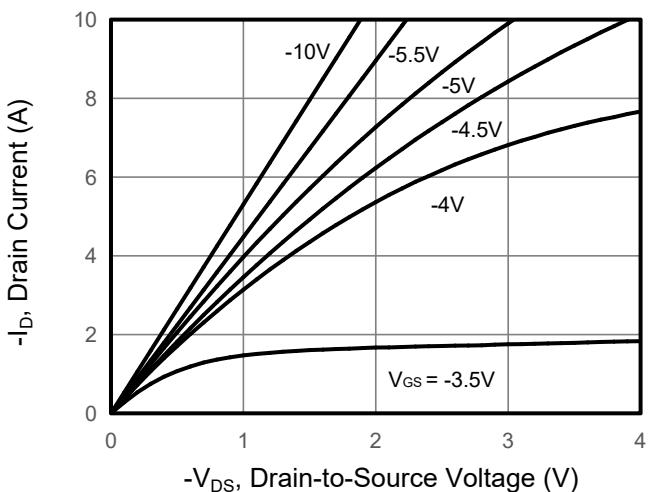


EAS Test Circuit

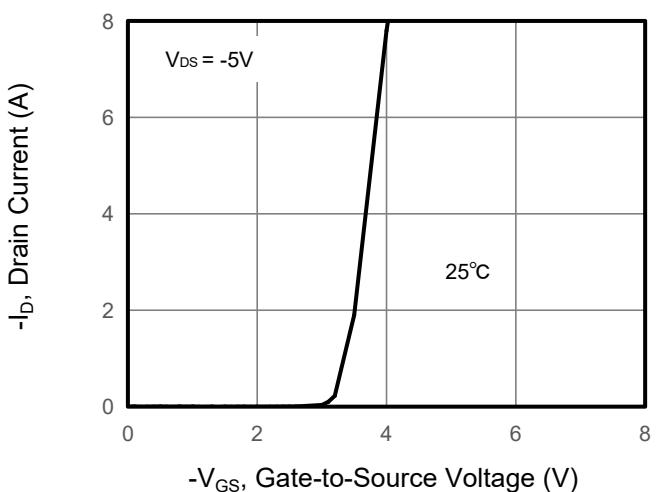


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

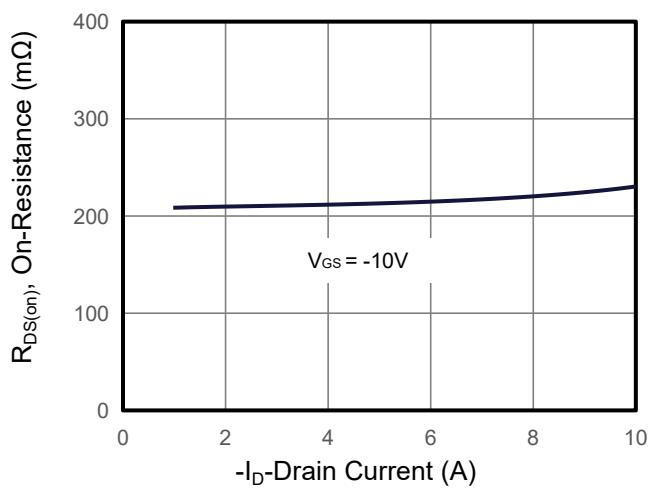
**Figure 1. Output Characteristics**



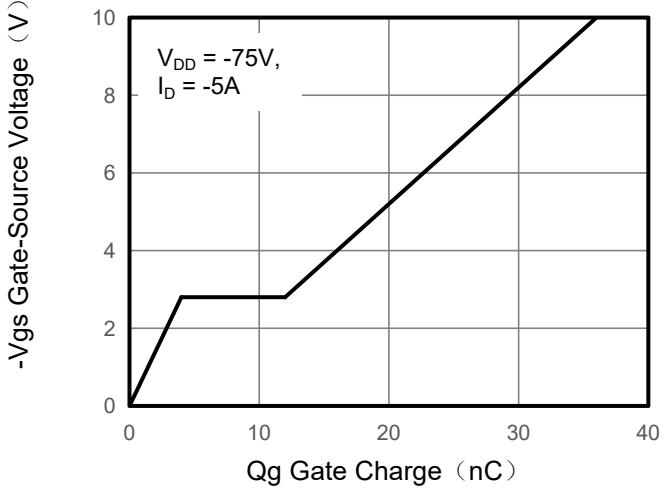
**Figure 2. Transfer Characteristics**



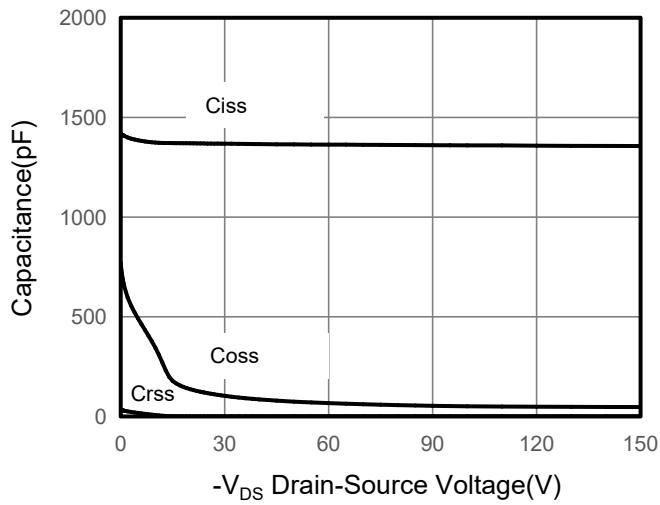
**Figure 3. Drain Source On Resistance**



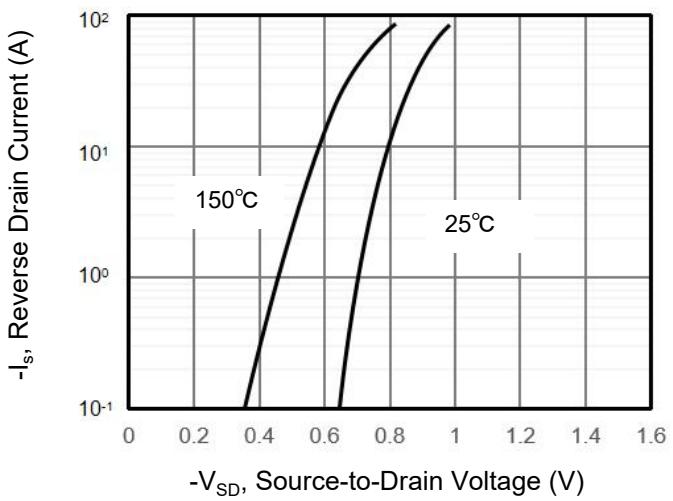
**Figure 4. Gate Charge**



**Figure 5. Capacitance**

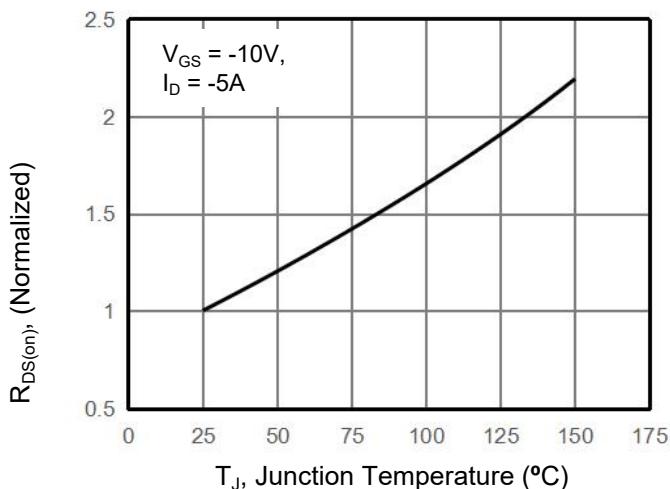


**Figure 6. Source-Drain Diode Forward**

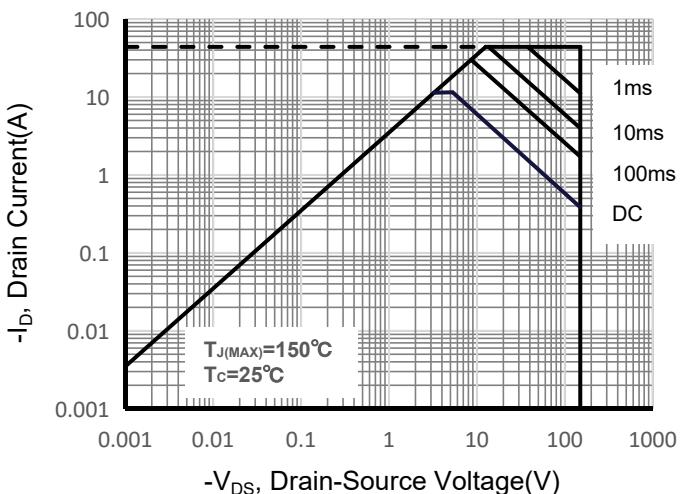


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

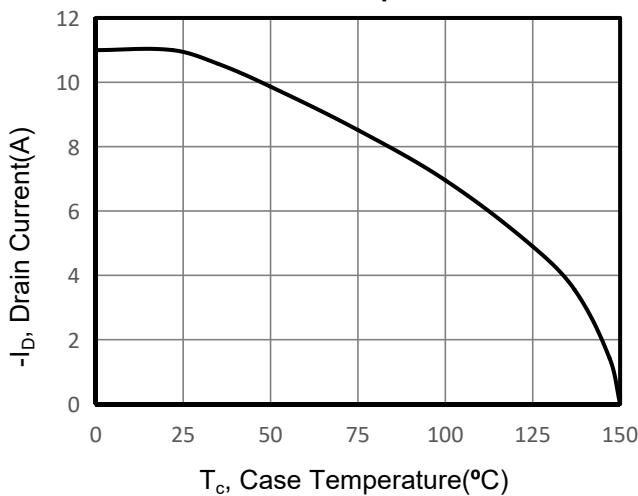
**Figure 7. Drain-Source On-Resistance**



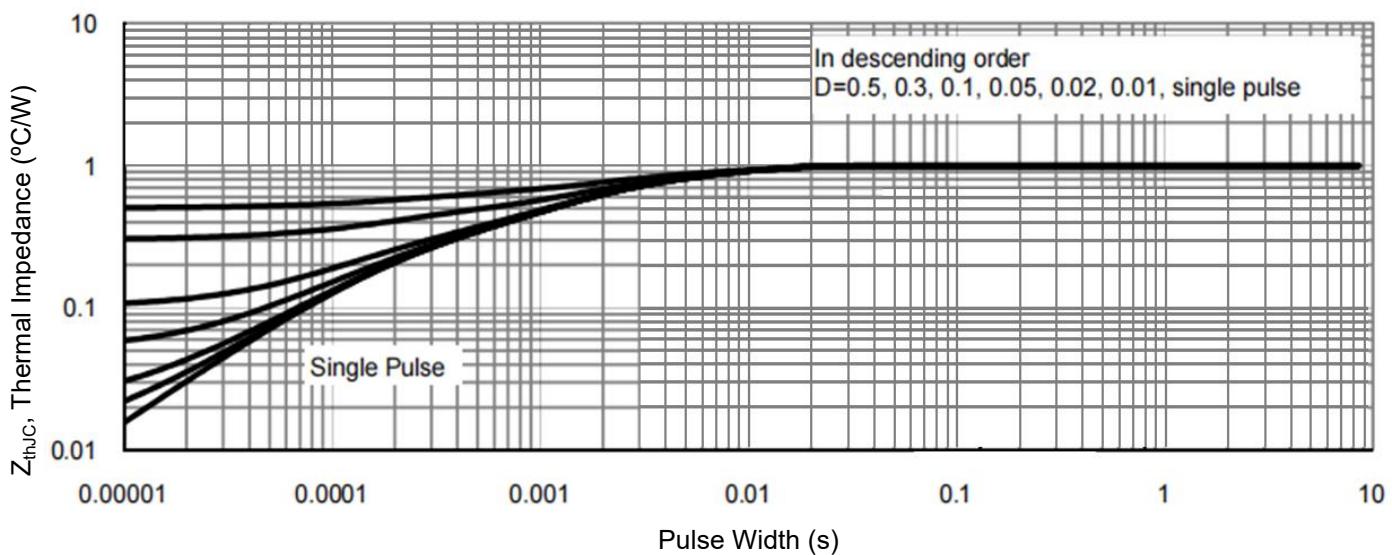
**Figure 8. Safe Operation Area**



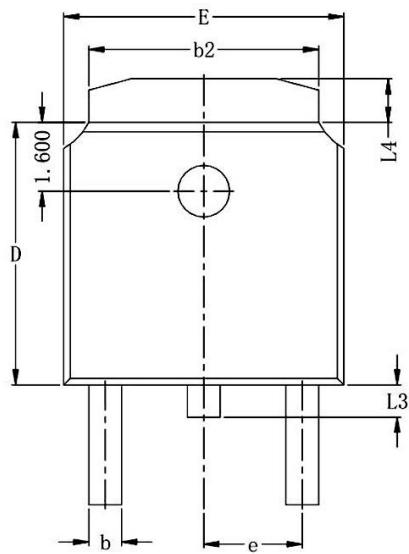
**Figure 9. Maximum Continuous Drain Current vs Case Temperature**



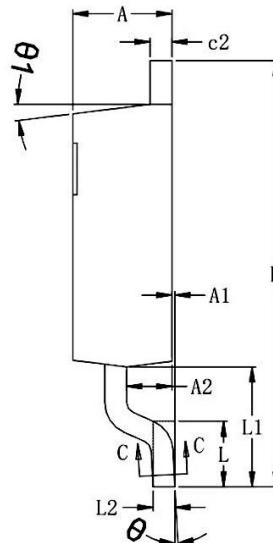
**Figure 10. Normalized Maximum Transient Thermal Impedance**



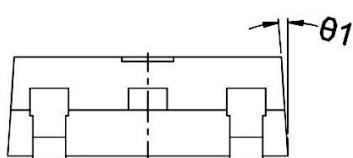
## TO-252 Package Information



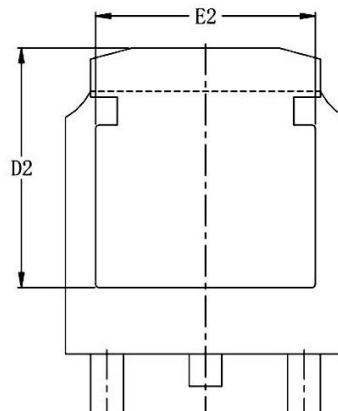
TOP VIEW



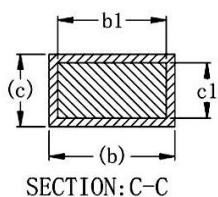
SIDE VIEW (Right)



SIDE VIEW (Front)



BOTTOM VIEW



SECTION: C-C

OPTION 1

DIM SYMBOL	MIN.	NOM.	MAX.	DIM SYMBOL	MIN.	NOM.	MAX.
A	2.200	2.300	2.400	E	6.400	6.500	6.600
A1	0.000	0.070	0.130	E2	4.900	5.100	5.300
A2	0.950	1.050	1.150	e	2.286 BSC.		
b	0.700	0.800	0.900	H	9.700	9.900	10.100
b1	0.660	0.760	0.860	L	1.380	1.525	1.725
b2	5.134	5.334	5.534	L1	2.588	2.788	2.988
c	0.448	0.548	0.648	L2	0.508 BSC.		
c1	0.458	0.508	0.558	L3	0.600	0.750	0.950
c2	0.448	0.548	0.648	L4	0.812	1.012	1.212
D	6.000	6.100	6.200	θ	1°	3°	5°
D2	5.372	5.572	5.772	θ1	6°	7°	8°